

MULTI-CHIP MODULE WITH BUILT-IN ELECTRONIC PART

Publication number: KR0158783B

Publication date: 1998-12-01

Inventor: YAMAMOTO TAKESHI (JP)

Applicant: NIPPON ELECTRIC CO (JP)

Classification:

- international: **H01L25/18; H01L23/538; H01L25/00; H01L25/04; H01L25/065; H01L25/07; H01L25/18; H01L23/52; H01L25/00; H01L25/04; H01L25/065; H01L25/07;**
(IPC1-7): H01L23/52

- European: H01L23/538F; H01L25/065N

Application number: KR19950033153 19950929

Priority number(s): JP19940235149 19940929

Also published as:



US5633783 (A1)

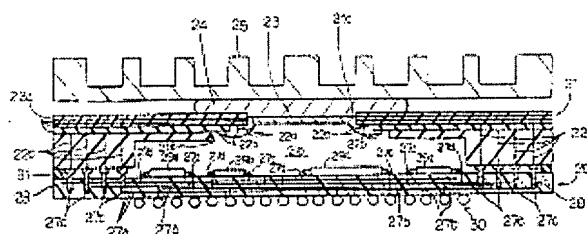
JP8097352 (A)

Report a data error here

Abstract not available for KR0158783B

Abstract of corresponding document: **US5633783**

Multi-layer wiring structures are respectively formed in upper and lower ceramic substrates for electric parts, and interconnecting pins held in contact with contact pads establish electrical connections between the multi-layer wiring structures so as to prevent a multi-chip module from an undesirable disconnection between the multi-layer wiring structures.



Data supplied from the **esp@cenet** database - Worldwide